

OL-NX5P2190

wafer level chip-scale package; 9 bumps; body 1.36 x 1.36 x 0.51 mm (Backside coating included)

8 February 2016

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	WLCSP
Package type industry code	WLCSP9
Package style descriptive code	UC (uncased chip)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	14-2-2014

Table 1. Package summary

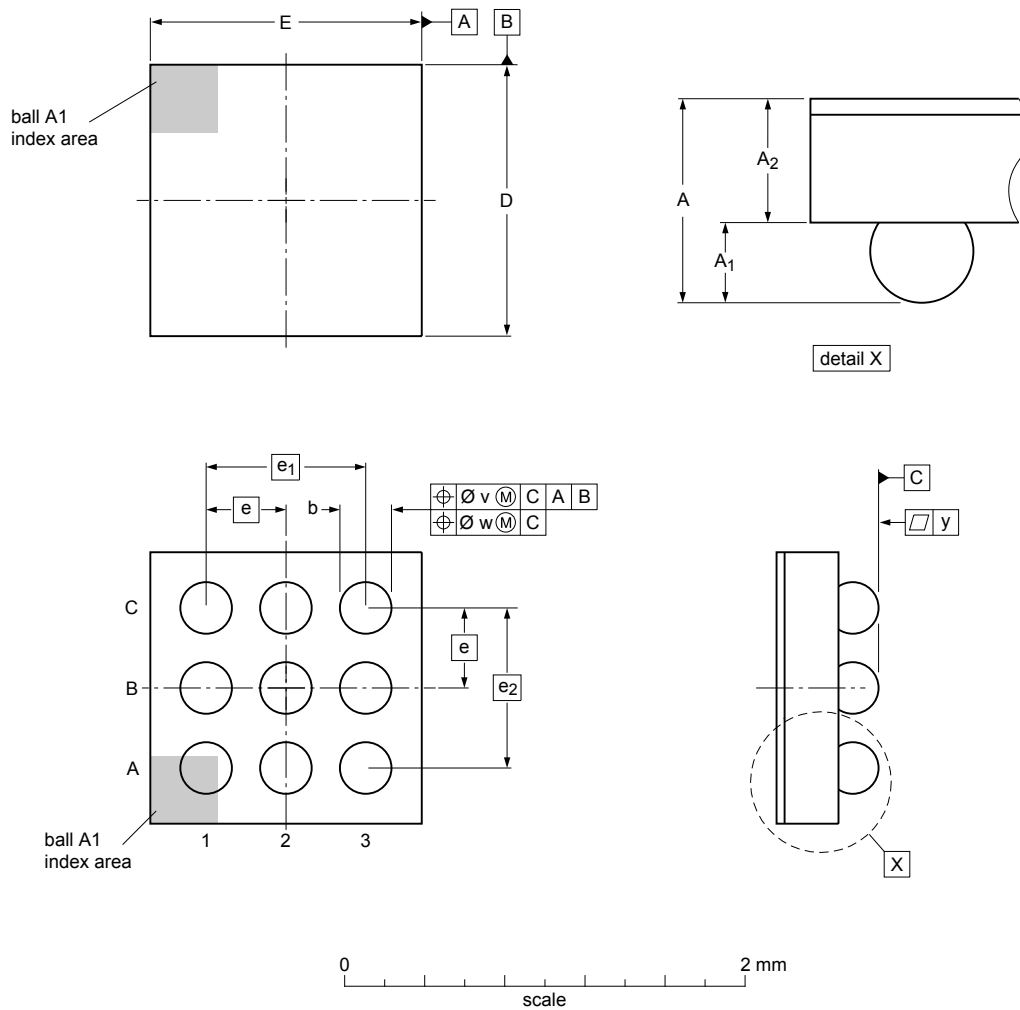
Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	1.33	-	1.36	1.39	mm
E	package width	1.33	-	1.36	1.39	mm
A	seated height	0.47	-	0.51	0.55	mm
e	nominal pitch	-	-	0.4	-	mm
n ₂	actual quantity of termination	-	-	9	-	



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2. Package outline

WLCSP9: wafer level chip-scale package;
9 bumps; body 1.36 x 1.36 x 0.51 mm (Backside coating included) NX5P2190UK



Dimensions (mm are the original dimensions)

Unit	A	A ₁	A ₂	b	D	E	e	e ₁	e ₂	v	w	y
mm	max 0.55	0.23	0.34	0.29	1.39	1.39						
	nom 0.51	0.20	0.31	0.26	1.36	1.36	0.4	0.8	0.8	0.05	0.015	0.03
	min 0.47	0.17	0.29	0.23	1.33	1.33						

nx5p2190uk_po

Outline version	References			European projection	Issue date
	IEC	JEDEC	JEITA		
NX5P2190UK					-14-02-12- 14-02-14

Fig. 1. Package outline WLCSP9 (OL-NX5P2190)

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3. Legal information

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